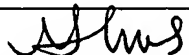


Substitute form 1449A/PTO		Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Application Number	not yet assigned
		Filing Date	03/02/2004
		First Named Inventor	Glenn A. Rinne
		Group Art Unit	1725
		Examiner Name	10790967
Sheet	1	of	1
		Attorney Docket Number	9180-10CT

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OTHER NON PATENT LITERATURE DOCUMENTS					T
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Examiner Signature		Date Considered	10/21/2005
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.